

2-CHANNEL COMMON-SOURCE POWER DMOS ARRAY

SLIS017 – SEPTEMBER 1992

- Two 7.5-A Independent Output Channels, Continuous Current Per Channel
- Low $r_{DS(on)}$. . . 0.09 Ω Typical
- Output Voltage . . . 60 V
- Pulsed Current . . . 15 A Per Channel
- Avalanche Energy . . . 120 mJ

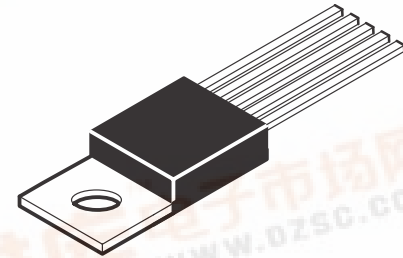
KC PACKAGE
(TOP VIEW)



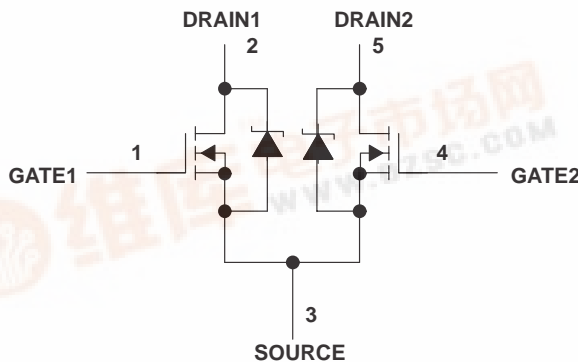
The tab is electrically connected to SOURCE.

description

The TPIC2202 is a monolithic power DMOS array that consists of two independent N-channel enhancement-mode DMOS transistors connected in a common-source configuration with open drains.



schematic



absolute maximum ratings over operating case temperature range (unless otherwise noted)

Drain-source voltage, V_{DS}	60 V
Gate-source voltage, V_{GS}	± 20 V
Continuous source-drain diode current	7.5 A
Pulsed drain current, each output, all outputs on, I_D (see Note 1)	15 A
Continuous drain current, each output, all outputs on	7.5 A
Single-pulse avalanche energy, E_{AS} (see Figure 4)	120 mJ
Continuous power dissipation at (or below) $T_A = 25^\circ\text{C}$ (see Note 2)	2 W
Continuous power dissipation at (or below) $T_C = 75^\circ\text{C}$, all outputs on (see Note 2)	31 W
Operating virtual junction temperature range, T_J	-40°C to 150°C
Operating case temperature range, T_C	-40°C to 125°C
Storage temperature range, T_{stg}	-40°C to 125°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

- NOTES: 1. Pulse duration = 10 ms, duty cycle = 6%
2. For operation above 25°C free-air temperature, derate linearly at the rate of 16 mW/ $^\circ\text{C}$. For operation above 75°C case temperature, and with all outputs conducting, derate linearly at the rate of 0.42 W/ $^\circ\text{C}$. To avoid exceeding the design maximum virtual junction temperature, these ratings should not be exceeded.



TPIC2202

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electrical characteristics, $T_C = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{(BR)DS}$ Drain-source breakdown voltage	$I_D = 1 \mu\text{A}$, $V_{GS} = 0$	60			V
V_{TGS} Gate-source threshold voltage	$I_D = 1 \text{mA}$, $V_{DS} = V_{GS}$	1.2	1.75	2.4	V
$V_{DS(on)}$ Drain-source on-state voltage	$I_D = 7.5 \text{A}$, $V_{GS} = 15 \text{V}$, See Notes 3 and 4		0.68	0.94	V
I_{DSS} Zero-gate-voltage drain current	$V_{DS} = 48 \text{V}$, $V_{GS} = 0$	$T_C = 25^\circ\text{C}$	0.07	1	μA
		$T_C = 125^\circ\text{C}$	1.3	10	
I_{GSSF} Forward gate current, drain short circuited to source	$V_{GS} = 20 \text{V}$, $V_{DS} = 0$		10	100	nA
I_{GSSR} Reverse gate current, drain short circuited to source	$V_{GS} = -20 \text{V}$, $V_{DS} = 0$		10	100	nA
$r_{DS(on)}$ Static drain-source on-state resistance	$V_{GS} = 15 \text{V}$, $I_D = 7.5 \text{A}$, See Notes 3 and 4 and Figures 5 and 6	$T_C = 25^\circ\text{C}$	0.09	0.125	Ω
		$T_C = 125^\circ\text{C}$	0.15	0.21	
g_{fs} Forward transconductance	$V_{DS} = 15 \text{V}$, $I_D = 5 \text{A}$, See Notes 3 and 4	2.5	4.7		S
C_{iss} Short-circuit input capacitance, common source	$V_{DS} = 25 \text{V}$, $V_{GS} = 0$, $f = 300 \text{kHz}$		490		pF
C_{oss} Short-circuit output capacitance, common source			285		
C_{rss} Short-circuit reverse transfer capacitance, common source			90		

NOTES: 3. Technique should limit $T_J - T_C$ to 10°C maximum.

4. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

source-drain diode characteristics, $T_C = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{SD} Forward on voltage	$I_S = 7.5 \text{A}$, $V_{GS} = 0$, $di/dt = 100 \text{A}/\mu\text{s}$, $V_{DS} = 48 \text{V}$, See Figure 1		0.8	1.3	V
t_{rr} Reverse recovery time			200		ns
Q_{RR} Total source-drain diode charge			1.5		μC

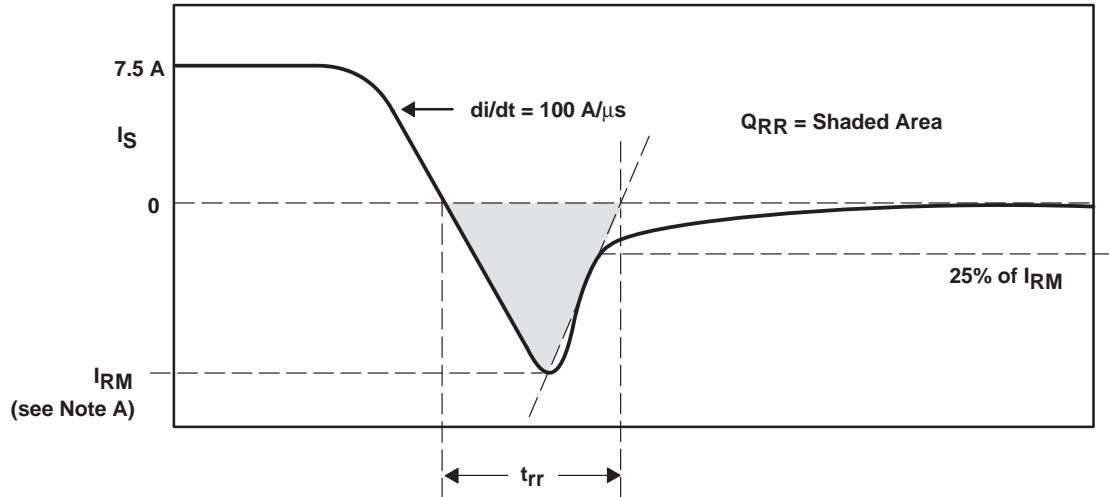
resistive-load switching characteristics, $T_C = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{d(on)}$ Turn-on delay time	$V_{DD} = 25 \text{V}$, $R_L = 6.7 \Omega$, $t_{en} = 10 \text{ns}$, $t_{dis} = 10 \text{ns}$, See Figure 2		12		ns
$t_{d(off)}$ Turn-off delay time			100		
t_r Rise time			43		
t_f Fall time			5		
Q_g Total gate charge	$V_{DD} = 48 \text{V}$, $I_D = 2.5 \text{A}$, $V_{GS} = 10 \text{V}$, See Figure 3		13.6	18	nC
Q_{gs} Gate-source charge			8.3	11	
Q_{gd} Gate-drain charge			5.3	7	
L_D Internal drain inductance			7		nH
L_S Internal source inductance			7		

thermal resistance

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$R_{\theta JA}$ Junction-to-ambient thermal resistance	All outputs with equal power			62.5	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$ Junction-to-case thermal resistance	All outputs with equal power			2.4	$^\circ\text{C}/\text{W}$
	One output dissipating power			3.3	$^\circ\text{C}/\text{W}$

PARAMETER MEASUREMENT INFORMATION



NOTE A: I_{RM} = maximum recovery current

Figure 1. Reverse-Recovery-Current Waveforms of Source-Drain Diode

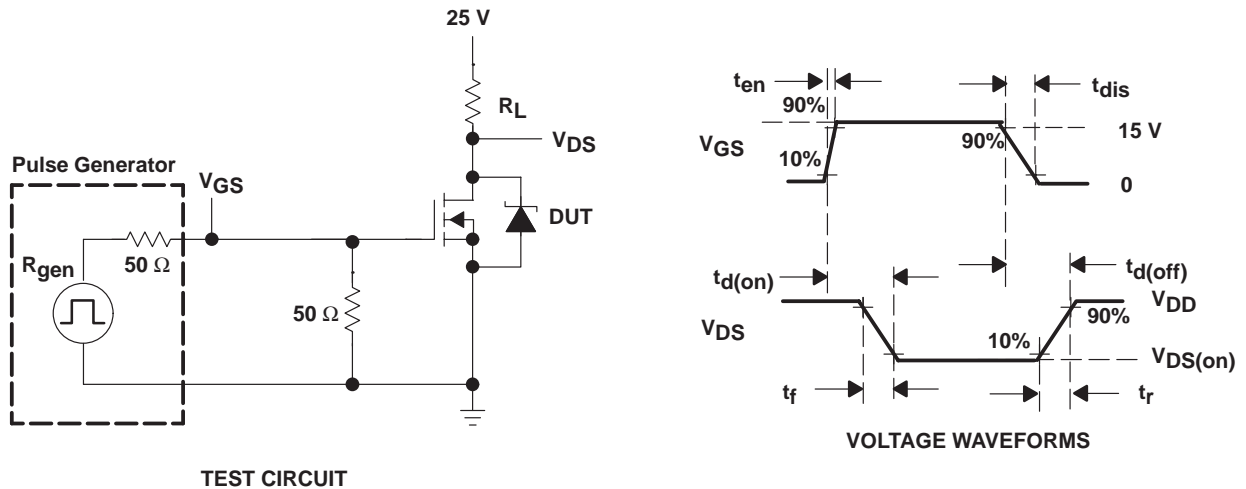


Figure 2. Test Circuit and Voltage Waveforms, Resistive Switching

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PARAMETER MEASUREMENT INFORMATION

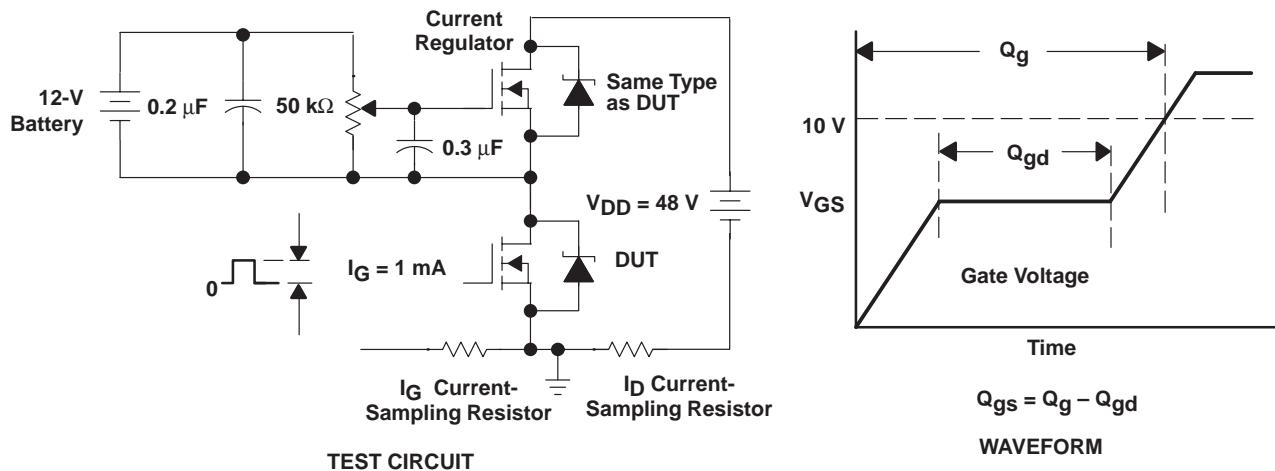
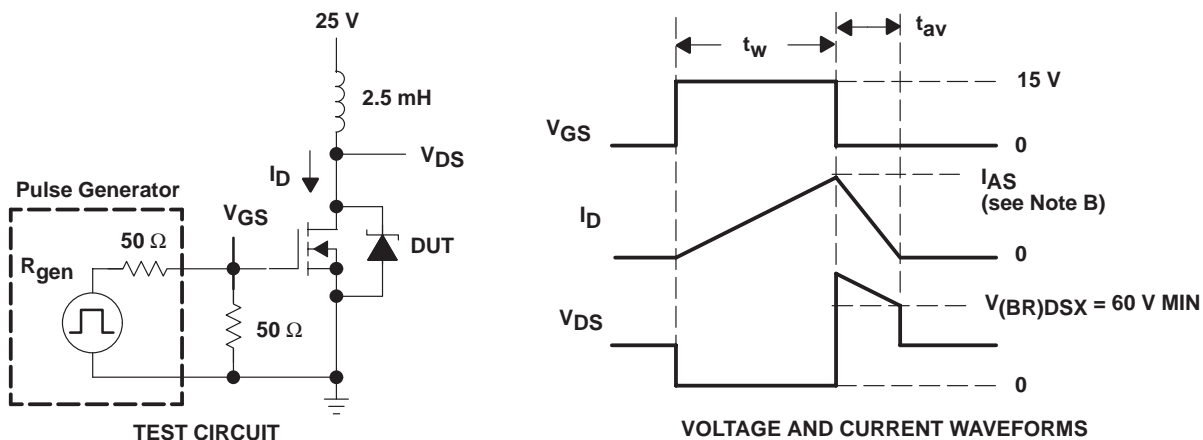


Figure 3. Gate Charge Test Circuit and Waveform



- NOTES: A. The pulse generator has the following characteristics: $t_r \leq 10$ ns, $t_f \leq 10$ ns, $Z_O = 50 \Omega$.
 B. Input pulse duration (t_w) is increased until peak current $I_{AS} = 7.5$ A.

$$\text{Energy test level is defined as } E_{AS} = \frac{I_{AS} \times V_{(BR)DSX} \times t_{av}}{2} = 120 \text{ mJ min.}$$

Figure 4. Single-Pulse Avalanche Energy Test Circuit and Waveforms

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TYPICAL CHARACTERISTICS

**STATIC DRAIN-SOURCE ON-STATE RESISTANCE
vs
CASE TEMPERATURE**

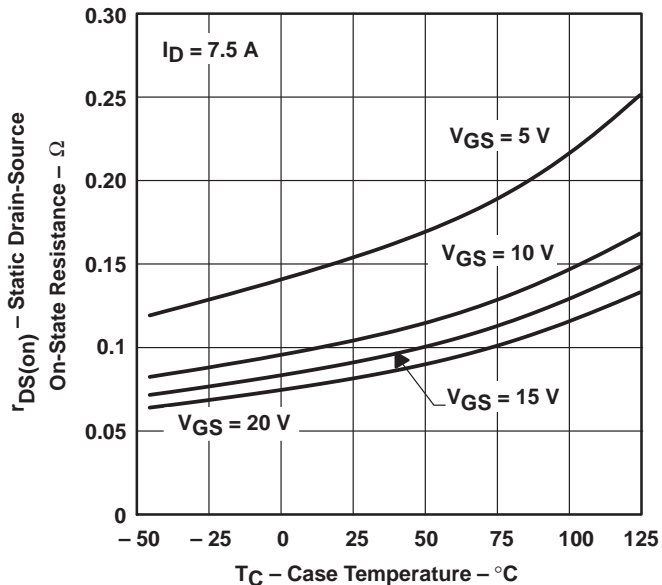


Figure 5

**STATIC DRAIN-SOURCE ON-STATE RESISTANCE
vs
DRAIN CURRENT**

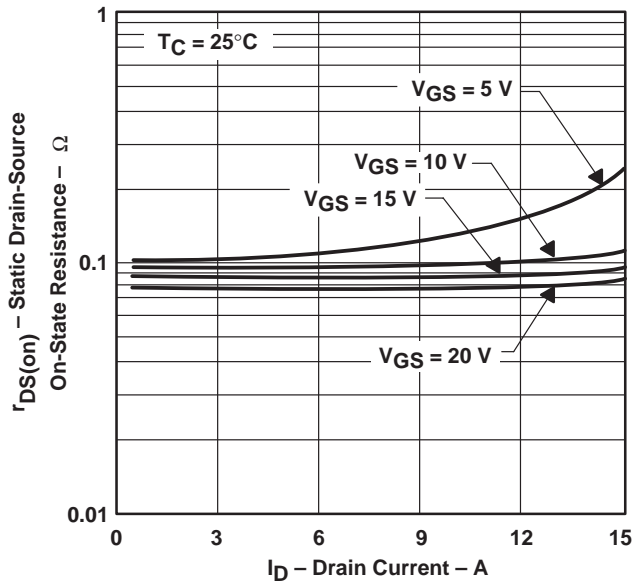


Figure 6

**DISTRIBUTION OF
FORWARD TRANSCONDUCTANCE**

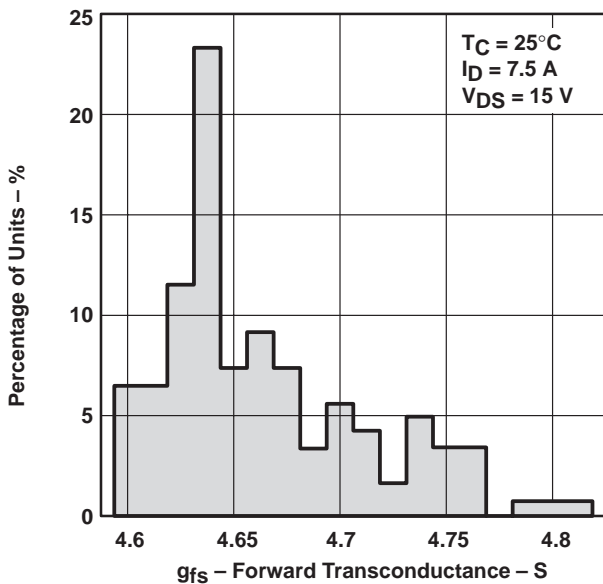


Figure 7

**DRAIN CURRENT
vs
DRAIN-TO-SOURCE VOLTAGE**

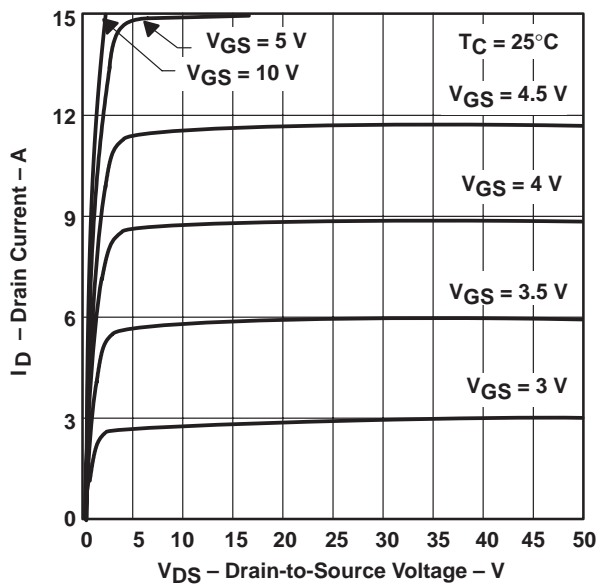


Figure 8

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TYPICAL CHARACTERISTICS

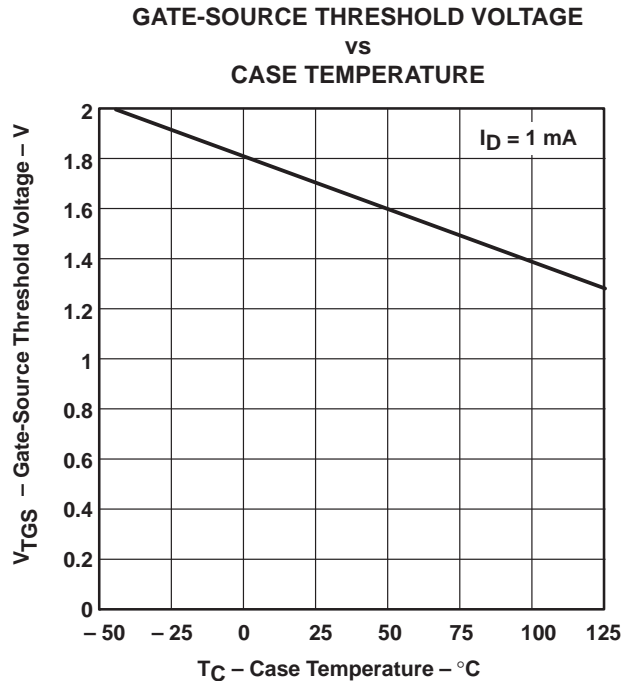


Figure 9

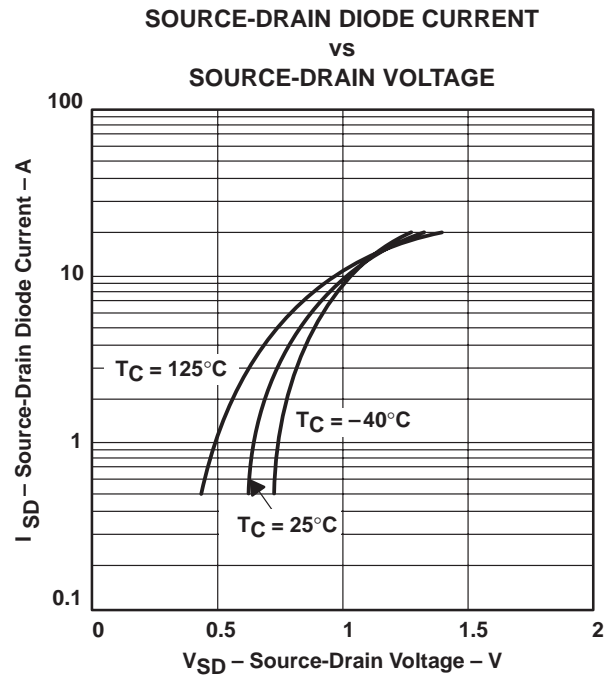


Figure 10

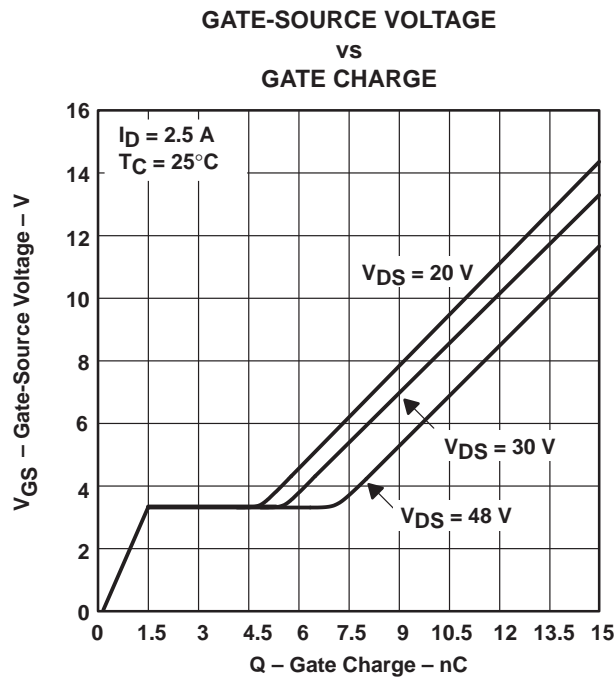


Figure 11

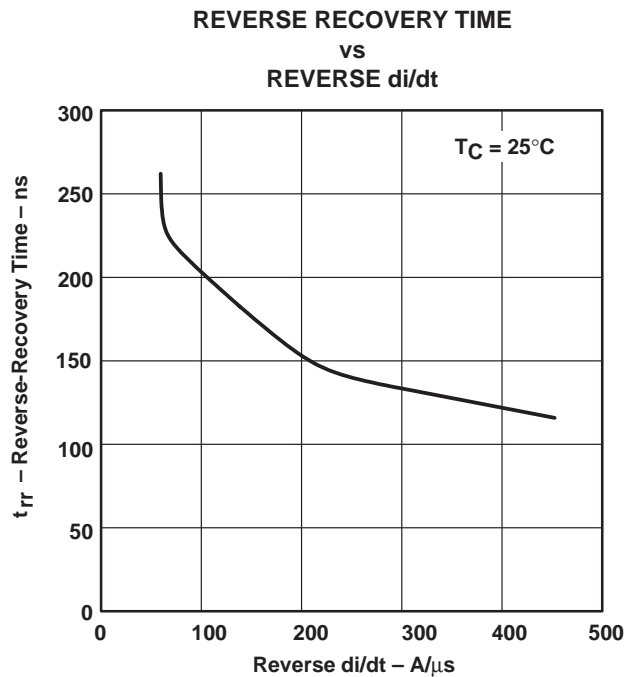


Figure 12

TYPICAL CHARACTERISTICS

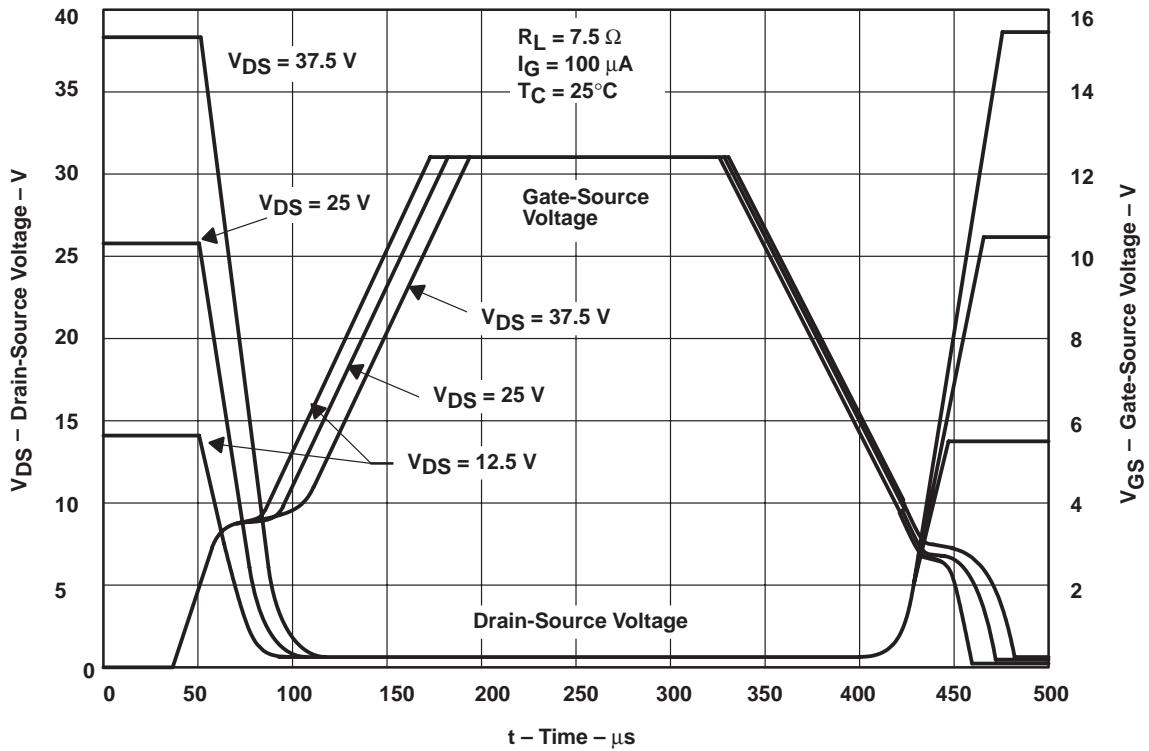


Figure 13. Resistive Switching Waveforms

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THERMAL INFORMATION

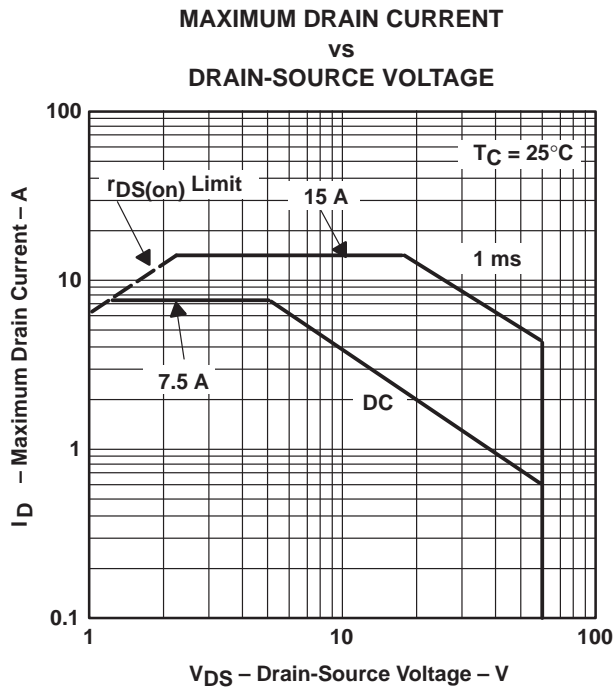


Figure 14

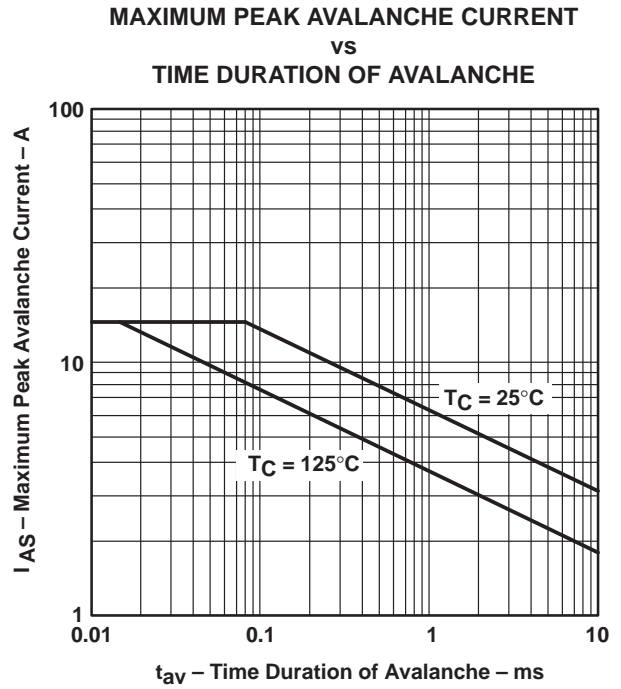
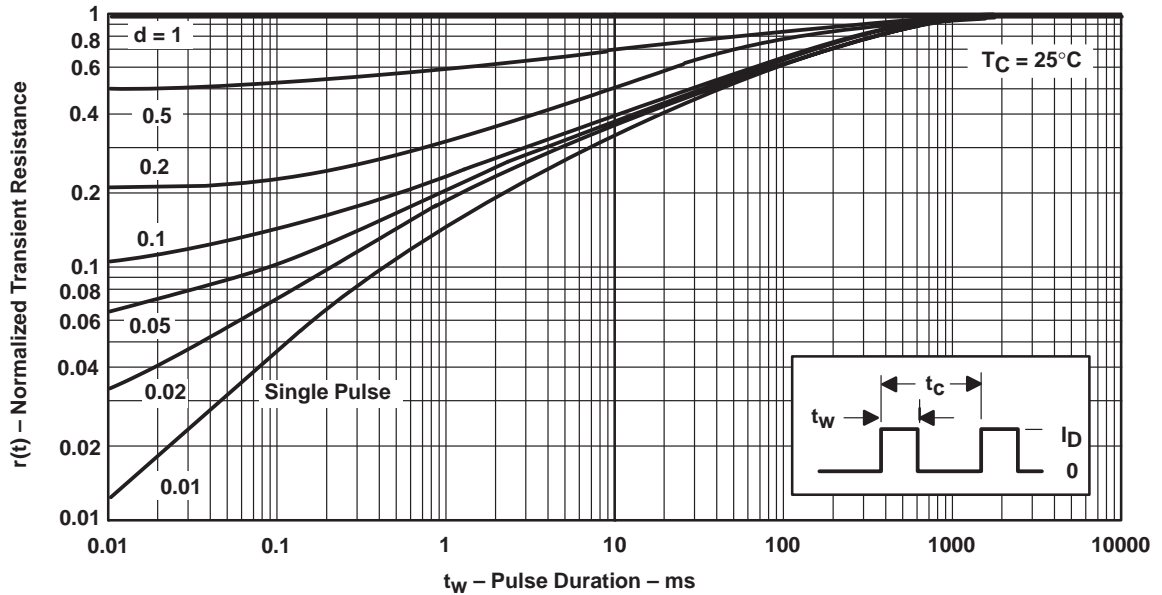


Figure 15

THERMAL INFORMATION

NORMALIZED TRANSIENT THERMAL IMPEDANCE
vs
SQUARE-WAVE PULSE DURATION



NOTES: $Z_{\theta JC}(t) = r(t) R_{\theta JC}$
 t_w = pulse duration
 t_c = period
 d = duty cycle = t_w/t_c

Figure 16

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